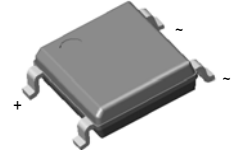




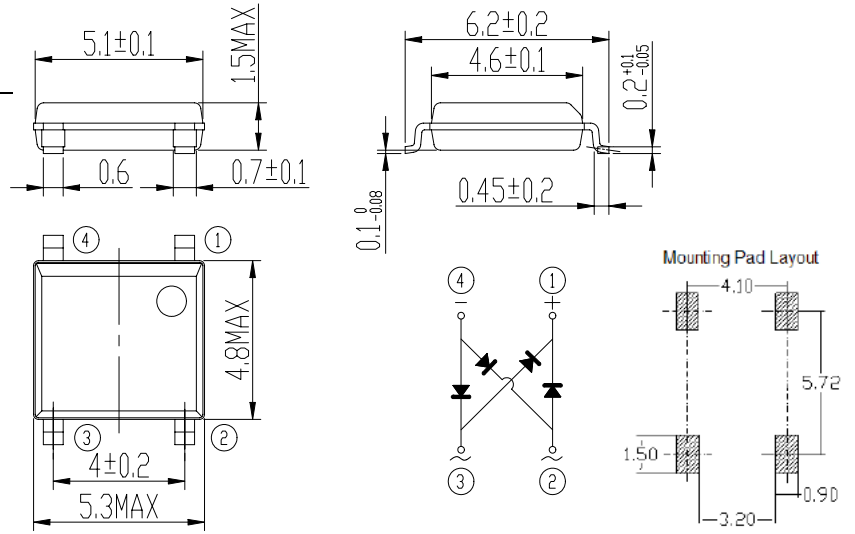
**Features**

- Low Profile: Typical height of 1.4mm
- Ideal for automated placement
- High surge current capability
- Solder Dip 260 , 10seconds



**Mechanical Data**

- Case:SOPA-4
- Epoxy meets UL-94V-0 Flammability rating
- Terminals:Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity:As markde on body



**Maximum Ratings & Electrical Characteristics** Ratings at 25

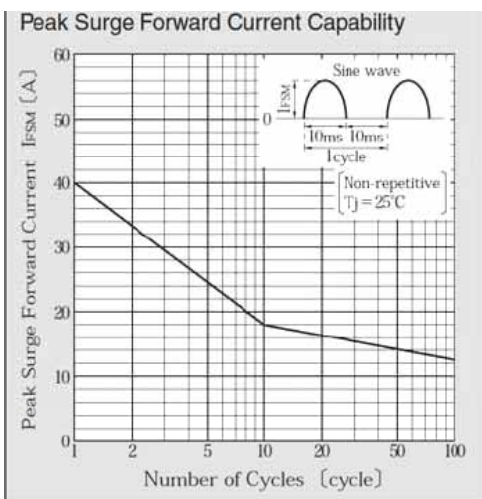
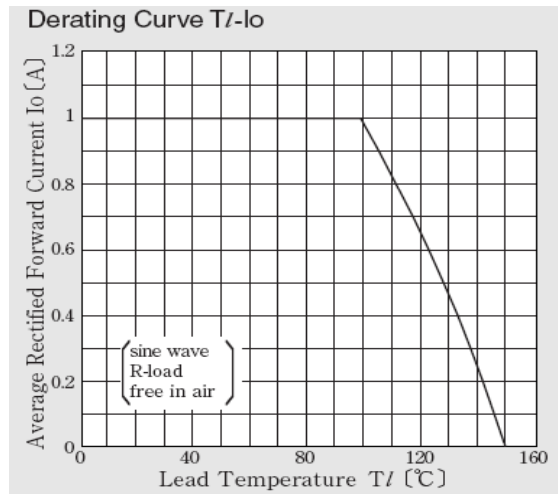
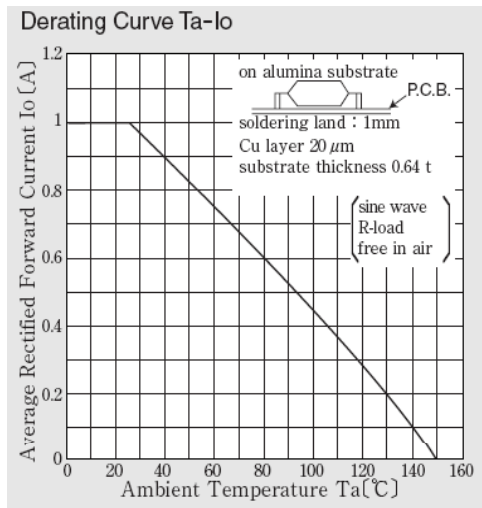
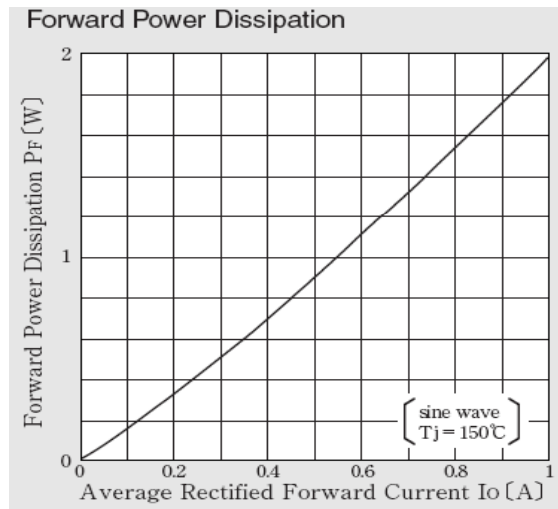
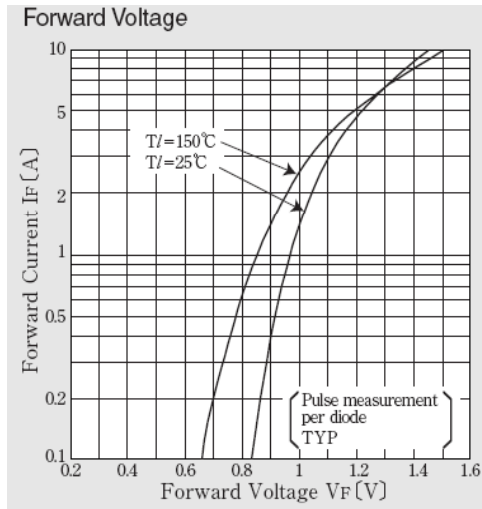
ambient temperature unless otherwise specified.

Parameter	Symbol	LB2SB	LB4SB	LB6SB	LB8SB	LB10SB	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I_{F(AV)}$					0.8 1.0	A
Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$					40	A
Rating for fusig ( $t < 8.3ms$ )	$i^2t$					6.5	A <sup>2</sup> sec
Maximum instantaneous forward voltage drop per diode at 1.0A	$V_F$					1.00	V
Maximum DC reverse current at $T_A=25$ rated DC blocking voltage per leg $T_A=125$	$I_R$					5 500	$\mu A$
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$					80 25	/W
Operating junction temperature range	$T_J$					-55 to +150	
Storage temperature range	$T_{STG}$					-55 to +150	

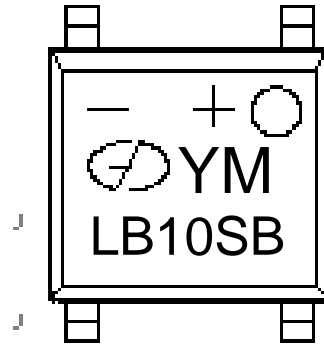
- Notes:** 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.  
2. JEDEC registered values

**RATINGS AND CHARACTERISTIC CURVES**

(TA=25 unless otherwise noted)



Marking



DATE CODE

Year	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020
Code	9	A	B	C	D	E	F	G	H	J	K	0
Month	1	2	3	4	5	6	7	8	9	10	11	12
Code	1	2	3	4	5	6	7	8	9	O	N	D